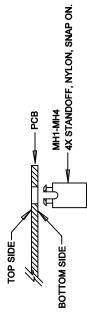


NOTES: UNLESS OTHERWISE SPECIFIED

- 1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
- 2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 C.
- 3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
- 4. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
- 5. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
- 6. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



APPROVALS	1630 MCCARTHY BLVD MILPITAS, CA 85035 PH; (409)432-1900	7 BLVD 5035 30
PCB DES.	TECHNOLOGY FOR CONFIDENTIAL- TECHNOLOGY FOR CONFIDENTIAL- TECHNOLOGY FOR COSTOMER USE ONLY	AL- SE ONLY
APP ENG.	TITLE: TOP ASSEMBLY DRAWING	
	WIDE INPUT RANGE, HIGH EFFICIENCY, SYNCHRONOUS BUCK CONVERTER WITH ACCURATE CURRENT LIMIT	NTLIMIT
	SIZE IC NO. LT3840EFE	REV.
	N/A DEMO CIRCUIT 1909A	2
SCALE NONE	EII ENAME: 1000A Down DCB	SHT 1 OF 2